

MC68040RC25 Information

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General Information

Parameter	Value
Part Number	MC68040RC25
Description	32BIT,FPU,CACHE,MMU
PTI	JBTG
Material Type	Tested Packaged Device
Life Cycle Description (code)	REMOVED FROM ACTIVE PORTFOLIO
Status	No Longer Manufactured

Package Information

Parameter	Value
Package Description	PGA 179 FG
JEDEC Pkg Description	PPGA-P179
Pin/Lead/Ball Count	179
Package Material	Plastic
Mounting Style	Through Hole
Tape & Reel	No

Environmental and Compliance Information

Parameter	Value
Pb-Free	Not Available
RoHS Compliant	Not Available
RoHS Certificate of Analysis (CoA)	Contact Us
Package Peak Temperature (°C)	Not Available

Ordering Information

Parameter	Value
Export Control Classification Number (US)	EAR99
Harmonized Tariff (US) Disclaimer	8542.31.0000
Budgetary Price QTY 1000+ (\$US)	-

Product/Process Change Notice (PCN)

Number	Type	Title	Issue Date	Effectivity Date
9048	Product Bulletin	TIC SUPPORT FOR QUALITY QUERIES IN EMEA	04 Aug 2003	05 Aug 2003
8219	Product Bulletin	MC68040 MOS11 QUALIFICATION	22 Nov 2002	23 Nov 2002
7258	Product Change Notice	TRANSFER PRODUCTS FROM TSC8	01 Mar 2002	10 Jun 2002
5606	Product Change Notice	MC68040XXYY WAFER FAB CHANGE TO TSC8	05 May 2000	13 Aug 2000
4253	Product Change Notice	MANUFACTURING PROCESS CHANGE FROM 1.25 MIL ALUMINUM WIRE TO 1.0 MIL ALUMINUM WIRE	19 Dec 1998	29 Mar 1999
4172	Product Bulletin	TRAY CONVERSION FROM FLUOROWARE TO LOCAL TRAY SUPPLIER (PMM)	15 Oct 1998	16 Oct 1998
3139	Product Change Notice	TRANSFER OF SPS PRODUCTS TO TSC3 WAFER FABRICATION SITE	27 Oct 1997	05 Feb 1998
3072	Product Bulletin	RESEND - STANDARDIZING MOTOROLA PACKING QUANTITY FOR ALL MC68030 AND MC68040 DEVICES IN THE PIN GRID ARRAY PACKAGE	14 Sep 1997	01 Oct 1997
2999	Product Bulletin	STANDARDIZING MOTOROLA PACKING QUANTITY FOR ALL MC68030 AND MC68040 DEVICES IN THE PIN GRID ARRAY PACKAGE	19 Aug 1997	01 Oct 1997
2612	Product Change Notice	CMP AND PLUG PROCESS FOR MOS 11 0.65U MATERIAL	20 Mar 1997	29 Jun 1997
2586	Product Bulletin	STANDARDIZING INK MARKING FOR ALL 32 X 32 CQFP'S	05 Mar 1997	01 Apr 1997